



AT-C³

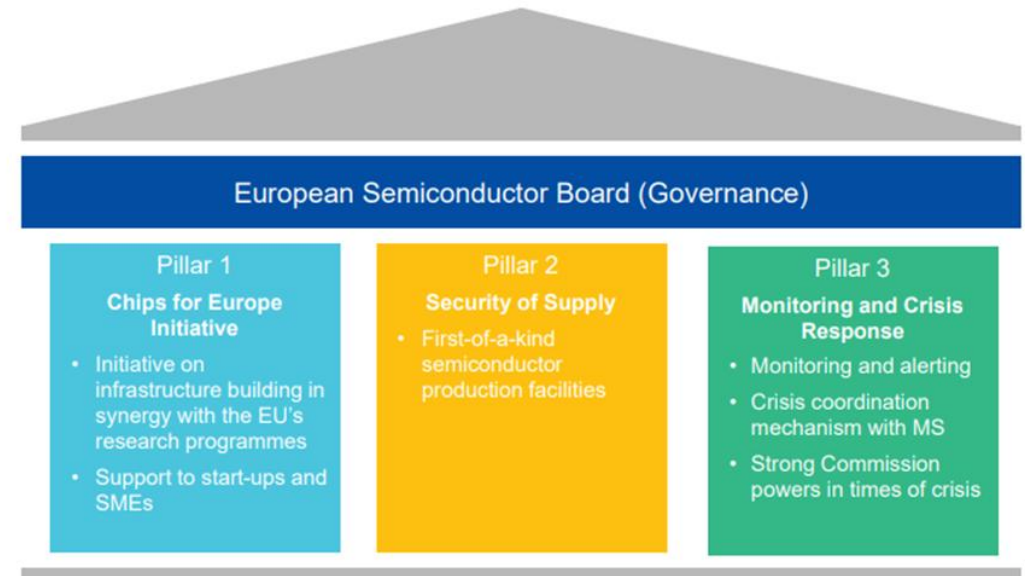
Austrian Chips
Competence Center

Uniting Research and Industry to Build
Europe's RISC-V Future

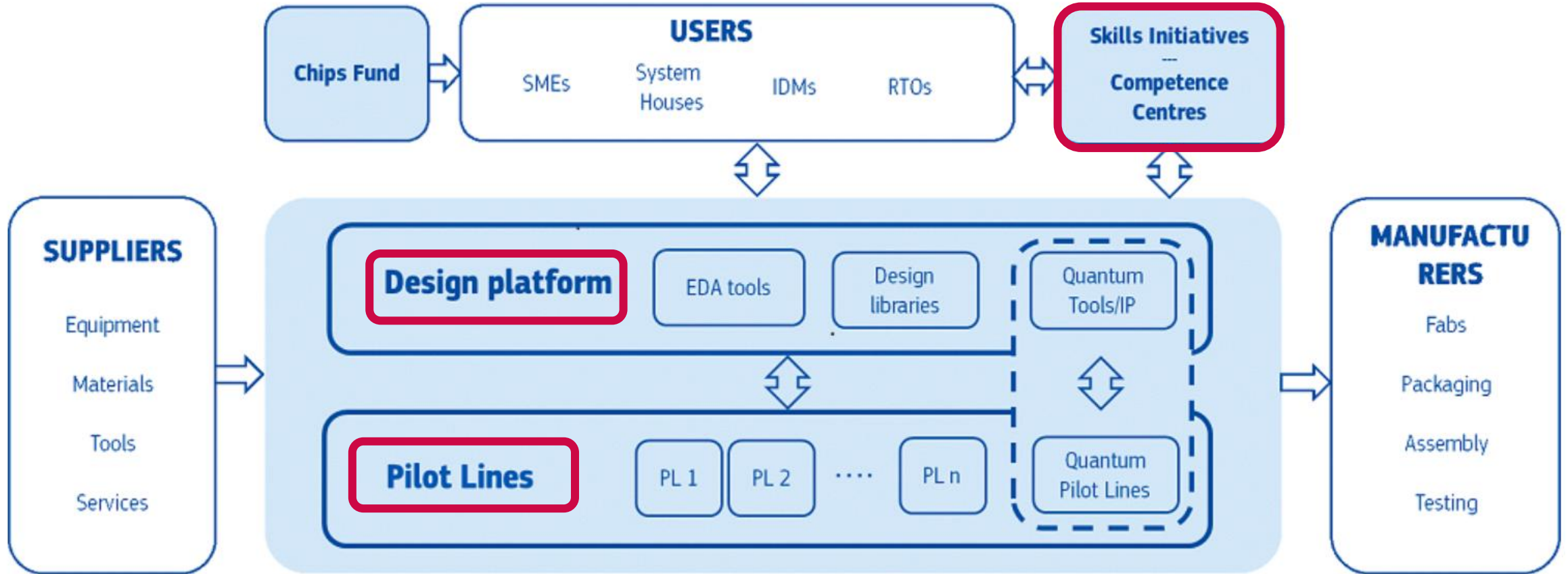
The EU Chips Act

2023 Edition

- Pillar 1: Chips for Europe initiative
 - Build up large-scale design capacities for integrated semiconductors technologies
 - Enhance existing and develop new **pilot lines**
 - Build advanced technology and engineering capacities for accelerating the development of quantum chips
 - Create a network of **competence centres** across Europe
 - Establish a **Chips Fund** to facilitate access to loans and equity by start-ups, scale-ups and SMEs and other companies in the semiconductor value chains.
- Pillar 2: Security of supply
 - Integrated Production Facility (IPF)
 - Open EU Foundry (OEF)
- Pillar 3: Monitoring and Crisis Response
 - Semiconductor supply chain monitoring



Overview of the Chips for Europe Initiative

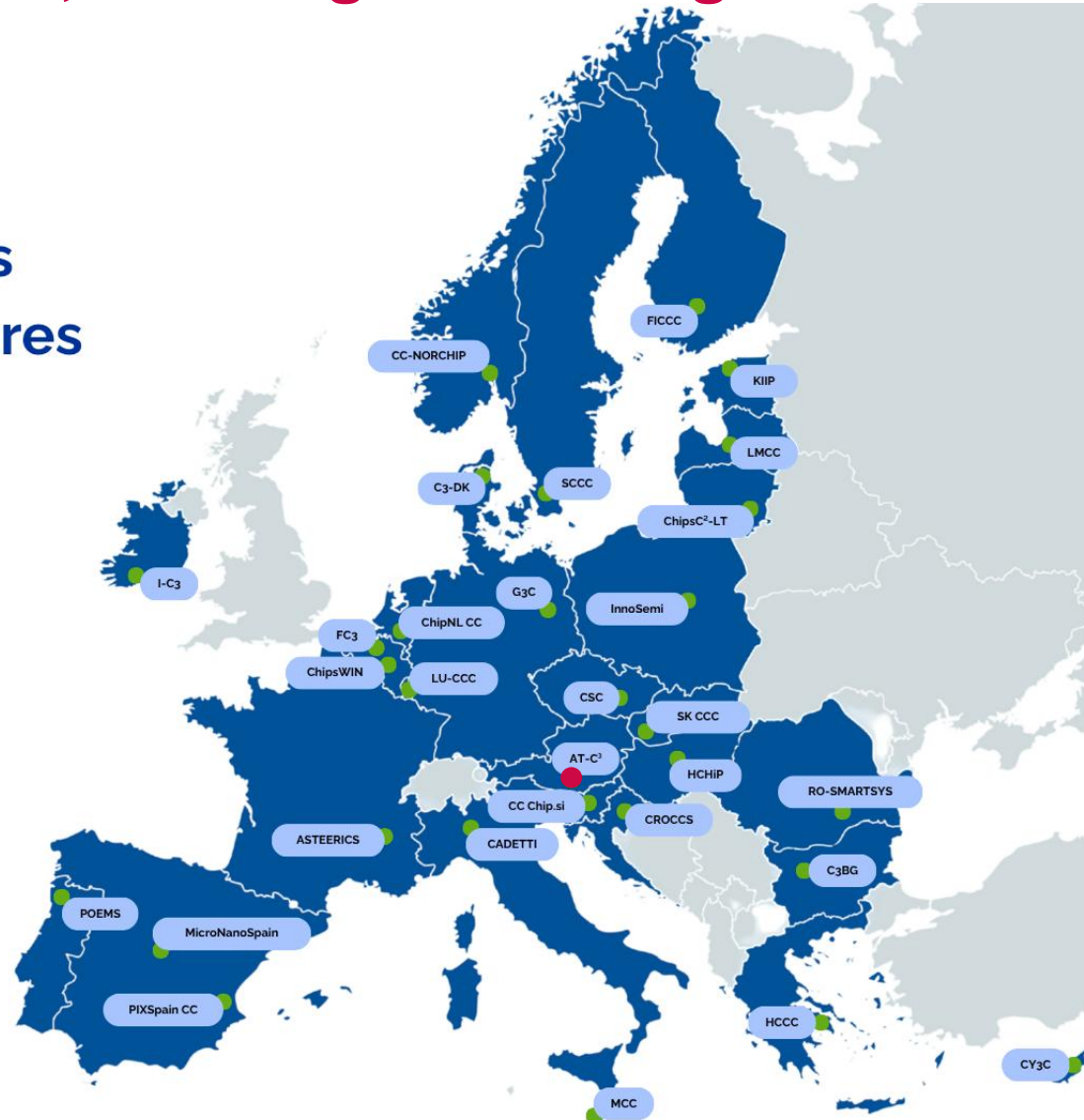


<https://digital-strategy.ec.europa.eu/en/factpages/european-chips-act-chips-europe-initiative>

The European Chips Competence Centers unite leading experts to drive innovation, exchange knowledge and deliver cutting-edge training.



30 European Chips Competence Centres



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[linkedin.com/company/aCCcess](https://www.linkedin.com/company/aCCcess)

aCCcess chatbot when asked about RISC-V



KIIP - Knowledge and Innovation in Integrated Processors (Estonia)

KIIP serves as Estonia's Chips Competence Centre and is focused on supporting fabless chip companies and technology providers. It places a strong emphasis on **open-source** technologies. Their services and expertise include:

Consulting and support for **RISC-V based open-source architectures**.[...]

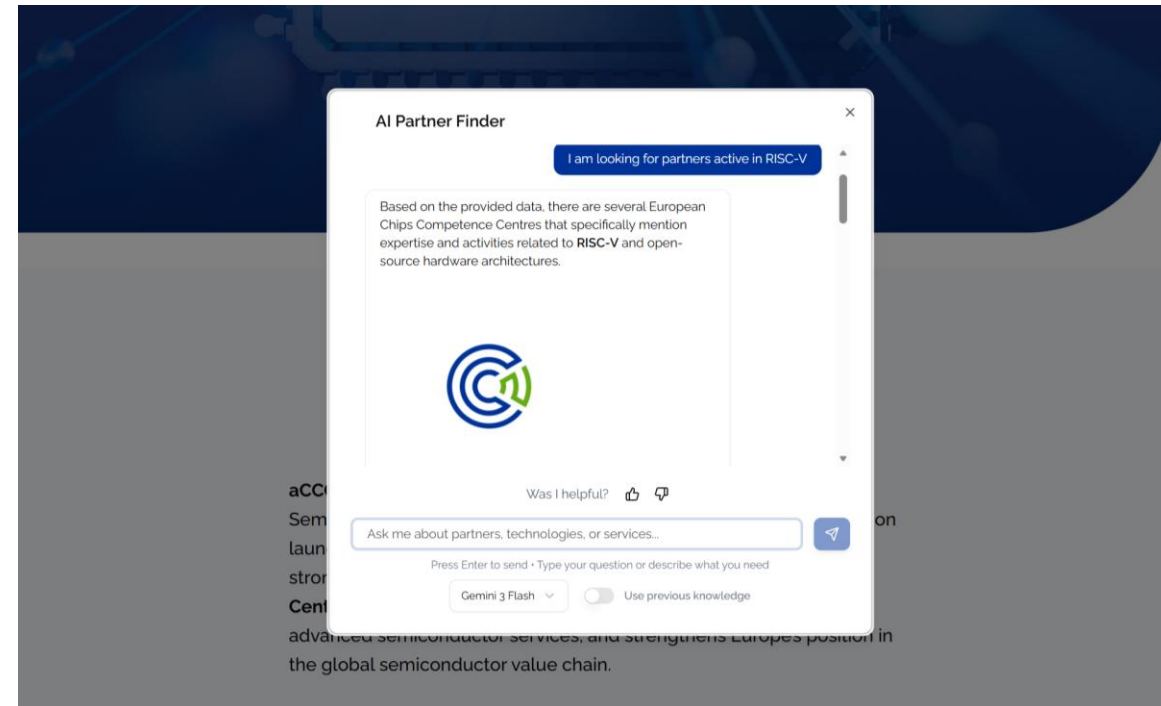
CADETTI - Italy's Chips Competence Centre

Its research and training divisions cover RF-to-THz technologies, analog and mixed-signal design, and digital design and **open hardware (including RISC-V)**

CSC - Czech Semiconductor Centre (Czech Republic)

The Czech Semiconductor Centre focuses on enhancing technical expertise in chip design and manufacturing within the Czech Republic. Its research areas and expertise domains include:

- Deployment and applications of **RISC-V-EDA**.
 - Deployment and demonstration of RISC-V-EDA for various applications including AI/ML and automotive.





AT-C³

Austrian Chips
Competence Center

Austrian Chips Competence Center
Opportunities for start-ups and SMEs

AT-C³ - Key facts



*Austria's Leading Center for Chip Design & Prototyping in Advanced Materials,
Thin Film Technologies and Quantum & Photonics*

Our Mission

AT-C³ acts as a central contact point - **“One-Stop-Shop”** - for companies and research organisations along the Electronic & Software-Based Systems (ESBS) value chain, focusing on supporting SMEs and startups.

Our consortium



AT-C³ services



We offer FUNDING

- Accessible for Austrian SMEs and startups
- Up to **80% funding** through innovation projects for the following topics:
 - Materials & Process Innovation
 - Chip Design & System Integration
 - Semiconductor Manufacturing

We provide ACCESS

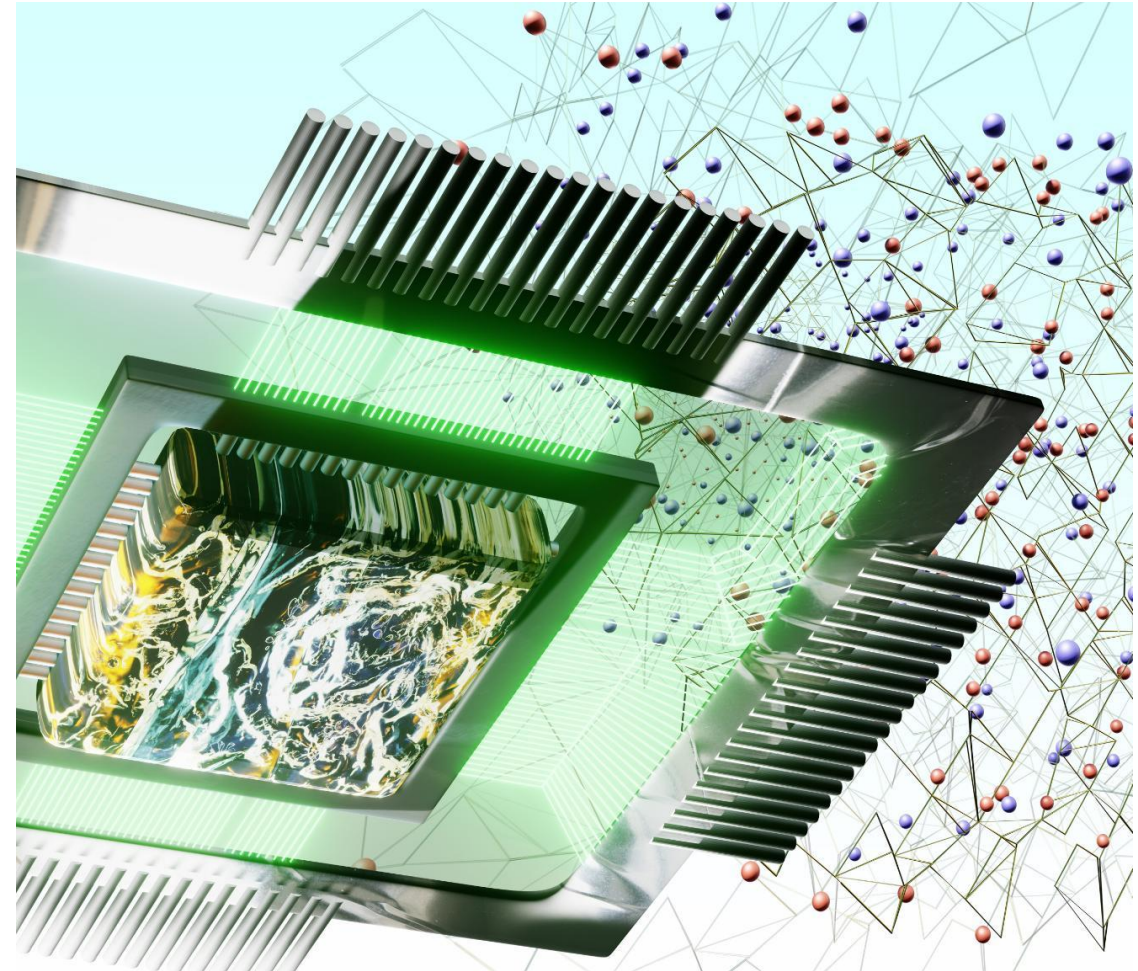
- Support in accessing the European Chip Design Platform
- Support in accessing the EU Pilot Lines
- Support in accessing Open Access EU Foundries

We provide FREE SERVICES

- Fully funded Skills & Training Programs starting from 2026
- Provision of financial expertise
- Access to EU Chips Fund
- Support in company valuations or co-investments, among other services

RISC-V & Chips Competence Center Shared Strategic Objectives

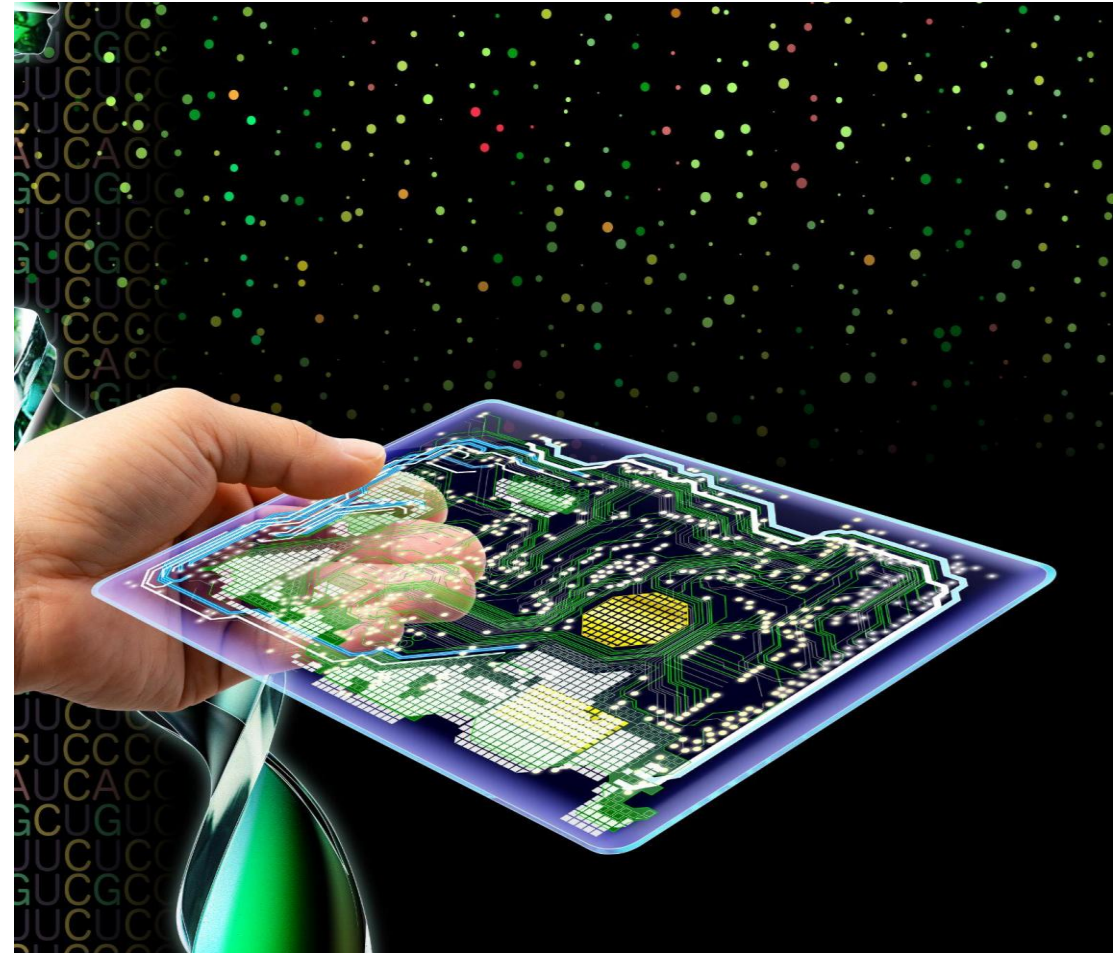
- Strengthening European technological sovereignty
- Enabling open, license-free CPU architectures
- Boosting innovation through collaborative semiconductor ecosystems
- Fostering cross-European research & industrial partnerships
- Supporting strategic autonomy in chip design and manufacturing



How AT-C³ can support the RISC-V community



- Joint R&D and innovation projects for RISC-V-based designs
- Training programs on chip design, embedded systems & open ISAs
- Access to the European Chips Design Platform (EDA tools, IP libraries, Funding)
- Access support for EU Pilot Lines (prototyping, manufacturing) and OA foundries
- Guidance on funding, investment & technology transfer for SMEs and startups





Austrian Chips Competence Center

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Project No. Chips JU: 101217532

Project No. FFG: FO999917171



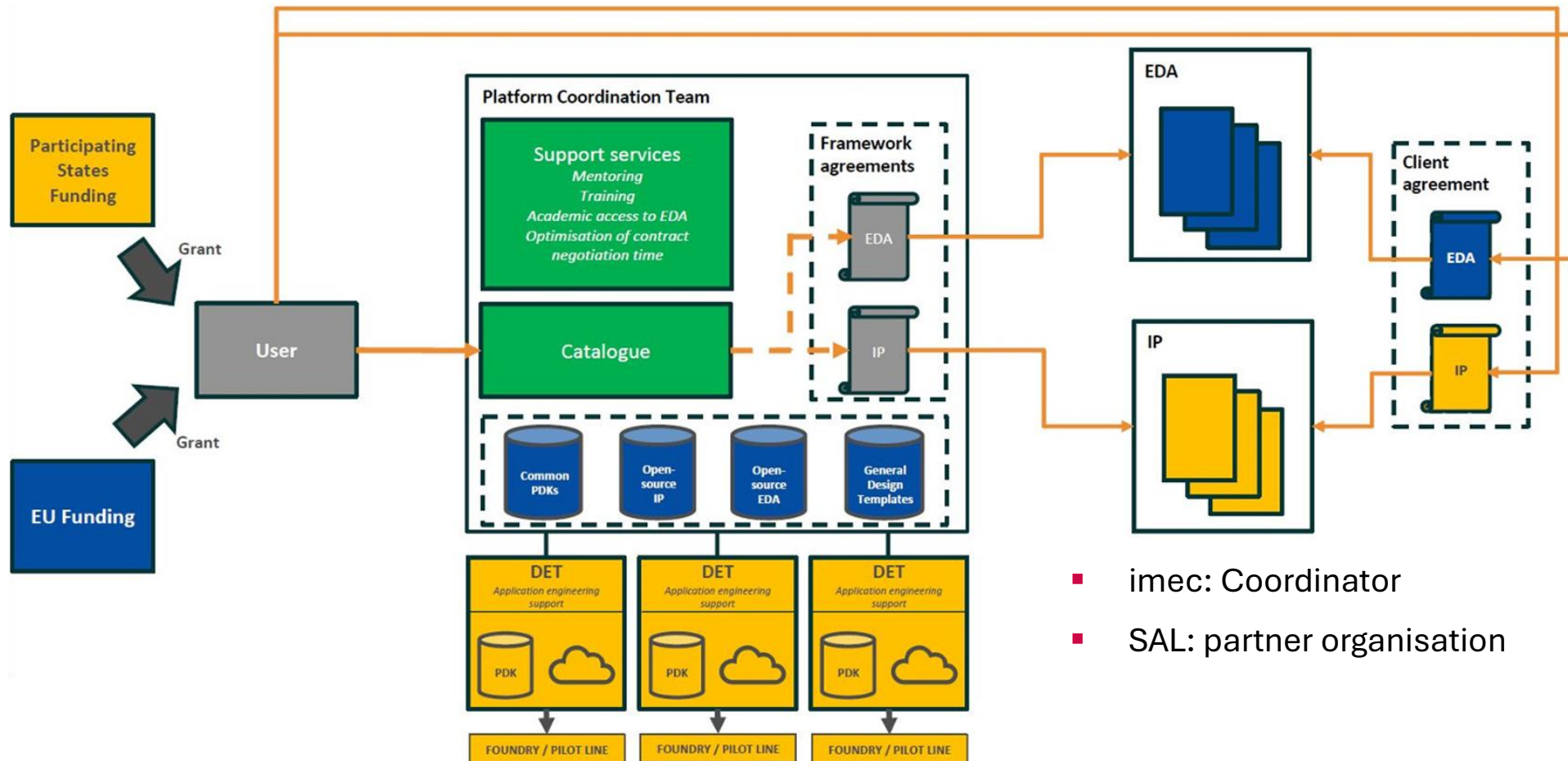
Kofinanziert von der
Europäischen Union



FT3 NATIONALSTIFTUNG
FORSCHUNG | TECHNOLOGIE | ENTWICKLUNG

The EU Chips Design Platform

Established under the European Chips Act, the platform will provide cloud-based access to semiconductor design tools, intellectual property (IP) libraries, training programs, pilot line technologies, and funding support services.















- imec: Coordinator
- SAL: partner organisation

AT-C³ & EU CHIPS ACT



Austria's Power for strengthening Europe's semiconductor ecosystem

PILOT LINES & DESIGN PLATFORM	QUANTUM PILOT ACTIONS	ALLIANCES - ENCCC
 	 	 
 	 	<p>DESIGN ENABLEMENT TEAMS</p>
 	 	 
 	 	<p>SKILLS COOPERATION</p>
 	 	 

ESTP project – Customer journey

Get fast and easy access to AT-C³ funding project

Eligible applicant for funding

- Austrian SMEs and startups operating along the ESBS value chain are eligible
- 40% of the project cost to be considered for the de-minimis

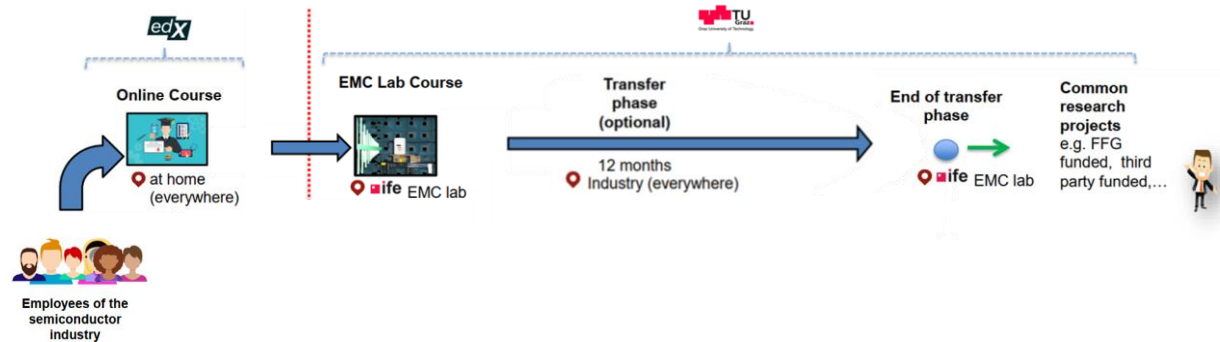
Eligible Projects and Costs

- Innovative project in the AT-C³ technology scope
- Technology Readiness Level (TRL) 5 or higher
- Project cost: 25.000 to 100.000* EUR
- Fast approval by the Project Evaluation Board within max. 8 weeks
- 80% funded
- 20% deductible (selbstbehalt) to be paid in-cash by the customer

Skills & Training Program



Free upskilling for the industry



Try our online course now:



Planned courses (first online courses in 2026):

- Advanced Materials Technology, Thermal Management, Analysis Chains in Microelectronics
- Introduction to Polymers in Electronics, Simulation of polymer, Sustainable polymer solutions & chemistry of functional polymers, Polymers & composites for structural applications, Smart Material Testing
- Sustainable materials for microelectronics, Thin film characterization and wafer-level processes
- Quantum communication and photonic integrated circuits, Ion-trap computing and photonics sensing, Cybersecurity, Threat analysis and Network protection
- Introduction to EMC, EMC Instrumentation, EMC aware System Design